Functional Safety Information

LM2901, LM2901B, LM2901V, LM2901AV Functional Safety FIT Rate, FMD and Pin FMA

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1 LM2901, LM2901B, LM2901V, LM2901AV Functional Safety FIT Rate, FMD and Pin FMA

1.1 Overview

This document contains information for LM2901, LM2901B, LM2901V, LM2901AV (TSSOP-14, SOIC-14 packages) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device
- Pin failure mode analysis (Pin FMA)

Figure 1-1 shows the device functional block diagram for reference.

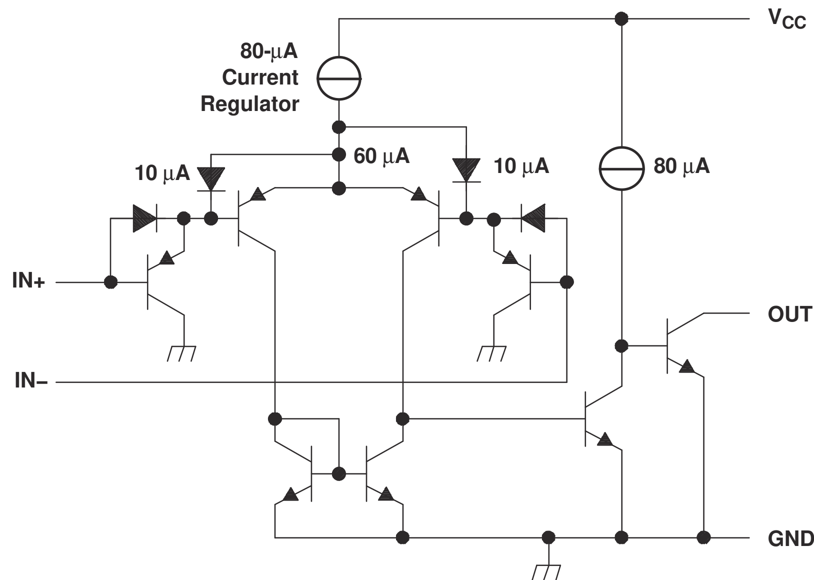

Figure 1-1. Functional Block Diagram

LM2901, LM2901B, LM2901V, LM2901AV was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

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1.2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for LM2901, LM2901B, LM2901V, LM2901AV based on two different industry-wide used reliability standards:

- Table 1-1 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- Table 1-2 provides FIT rates based on the Siemens Norm SN 29500-2

Table 1-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10^9 Hours)	
Package	TSSOP-14	SOIC-14
Total Component FIT Rate	10	16
Die FIT Rate	2	2
Package FIT Rate	8	14

The failure rate and mission profile information in Table 1-1 comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation12 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

Table 1-2. Component Failure Rates per Siemens Norm SN 29500-2

Table	Category	Reference FIT Rate	Reference Virtual T_J
4	CMOS, BICMOS Digital, analog / mixed	6 FIT	55°C

The Reference FIT Rate and Reference Virtual T_J (junction temperature) in Table 1-2 come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

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1.3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for LM2901, LM2901B, LM2901V, LM2901AV in Table 1-3 comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

Table 1-3. Die Failure Modes and Distribution

Die Failure Modes	Failure Mode Distribution (%)
Out open (HIZ)	15%
Out saturate high	25%
Out saturate low	25%
Out functional not in specification	30%
Short circuit any two pins	5%

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1.4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the LM2901, LM2901B, LM2901V, LM2901AV. The failure modes covered in this document include the typical pin-by-pin failure scenarios:

- Pin short-circuited to Ground (see Table 1-5)
- Pin open-circuited (see Table 1-6)
- Pin short-circuited to an adjacent pin (see Table 1-7)
- Pin short-circuited to supply (see Table 1-8)

Table 1-5 through Table 1-8 also indicate how these pin conditions can affect the device as per the failure effects classification in Table 1-4.

Table 1-4. TI Classification of Failure Effects

Class	Failure Effects
A	Potential device damage that affects functionality
B	No device damage, but loss of functionality
C	No device damage, but performance degradation
D	No device damage, no impact to functionality or performance

Figure 1-2 shows the LM2901-Q1, LM2901B-Q1, LM2901V-Q1, LM2901AV-Q1 pin diagram. For a detailed description of the device pins please refer to the '*Pin Configuration and Functions*' section in the data sheet.

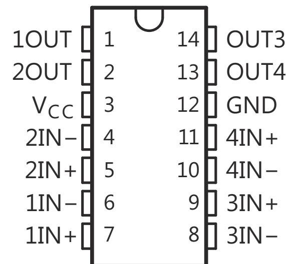

Figure 1-2. Pin Diagram

Table 1-5. Pin FMA for Device Pins Short-Circuited to Ground

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
1OUT	1	No change if GND pin is GND node	B
2OUT	2	No change if GND pin is GND node	B
VCC	3	Main supply shorted out (no power to device)	B
2IN-	4	Output goes high, if other input is positive	B
2IN+	5	Output goes low, if other input is positive	B
1IN-	6	Output goes high, if other input is positive	B
1IN+	7	Output goes low, if other input is positive	B
3IN-	8	Output goes high, if other input is positive	B
3IN+	9	Output goes low, if other input is positive	B
4IN-	10	Output goes high, if other input is positive	B
4IN+	11	Output goes low, if other input is positive	B
GND	12	No change if same node as GND	D
4OUT	13	No change if GND pin is GND node	B
3OUT	14	No change if GND pin is GND node	B

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Table 1-6. Pin FMA for Device Pins Open-Circuited

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
1OUT	1	Output can't drive application load	B
2OUT	2	Output can't drive application load	B
VCC	3	Main supply open (no power to device)	B
2IN-	4	Output may be low or high	B
2IN+	5	Output may be low or high	B
1IN-	6	Output may be low or high	B
1IN+	7	Output may be low or high	B
3IN-	8	Output may be low or high	B
3IN+	9	Output may be low or high	B
4IN-	10	Output may be low or high	B
4IN+	11	Output may be low or high	B
GND	12	Lowest voltage pin will drive GND pin internally (via diode)	A
4OUT	13	Output can't drive application load	B
3OUT	14	Output can't drive application load	B

Table 1-7. Pin FMA for Device Pins Short-Circuited to Adjacent Pin

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
1OUT	1	2OUT	Output may be low or high	B
2OUT	2	VCC	Thermal stress due to high power dissipation	A
VCC	3	2IN-	Output goes low, if other input is less positive	B
2IN-	4	2IN+	Output may be low or high	B
2IN+	5	1IN-	Output may be low or high	B
1IN-	6	1IN+	Output may be low or high	B
1IN+	7	3IN-	Output may be low or high	B
3IN-	8	3IN+	Output may be low or high	B
3IN+	9	4IN-	Output may be low or high	B
4IN-	10	4IN+	Output may be low or high	B
4IN+	11	GND	Output goes low, if other input is positive	B
GND	12	4OUT	No change if GND pin is GND node	B
4OUT	13	3OUT	Output may be low or high	B
3OUT	14	1OUT	Output may be low or high	B

Table 1-8. Pin FMA for Device Pins Short-Circuited to Supply

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
1OUT	1	Thermal stress due to high power dissipation	A
2OUT	2	Thermal stress due to high power dissipation	A
VCC	3	No change if same node as VCC	D
2IN-	4	Output goes low, if other input is less positive	B

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Table 1-8. Pin FMA for Device Pins Short-Circuited to Supply (continued)

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
2IN+	5	Output goes high, if other input is less positive	B
1IN-	6	Output goes low, if other input is less positive	B
1IN+	7	Output goes high, if other input is less positive	B
3IN-	8	Output goes low, if other input is less positive	B
3IN+	9	Output goes high, if other input is less positive	B
4IN-	10	Output goes low, if other input is less positive	B
4IN+	11	Output goes high, if other input is less positive	B
GND	12	Main supply shorted out (no power to device)	B
4OUT	13	Thermal stress due to high power dissipation	A
3OUT	14	Thermal stress due to high power dissipation	A

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